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Prepreg for laminate formation for printed circuit for high migration resistance - comprises glass cloth comprising glass fibres with low coefft of thermal expansion and high coating build-up of silane finishing agent with polyepoxy resin

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Patent Family

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Patent Details

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JP 8092394	A		6	C08J-005/24	

Abstract:

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A prepreg (I) is prepd. by impregnating the base material of glass cloth with a thermoset resin followed by drying. The glass cloth comprises glass fibres which have a coefft of thermal expansion of less than 4 ppm/deg. C and the coating build-up of a finishing agent on them of more than 0.15 wt. %, pref. more than 0.2 wt. %, to intensify the affinity with the thermoset resin. Also claimed is a laminate (II) prepd. from (I).

USE - (II) is used for printed circuit laminates.

ADVANTAGE - (II) has a low coefft. of thermal expansion and a high migration resistance.

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